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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/788,820	02/27/2004	Stuart Butterworth	COHP-5040	6927
28584 STALLMAN	7590 06/04/200 & POLLOCK LLP	8	EXAMINER	
353 SACRAMENTO STREET			FORDE, DELMA ROSA	
SUITE 2200 SAN FRANCI	SCO, CA 94111		ART UNIT	PAPER NUMBER
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			MAIL DATE	DELIVERY MODE
			06/04/2008	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)	
10/788,820	BUTTERWORTH ET AL.	
Examiner	Art Unit	
Delma R. Fordé	2828	

	Delma R. Forge	2828				
The MAILING DATE of this communication appe	ars on the cover sheet with the	orrespondence add	ress			
THE REPLY FILED 01 May 2008 FAILS TO PLACE THIS APPI	LICATION IN CONDITION FOR AL	LOWANCE.				
 The reply was filed after a final rejection, but prior to or on application, applicant must timely file one of the following application in condition for allowance; (2) a Notice of Apper for Continued Examination (RCE) in compliance with 37 C periods: 	replies: (1) an amendment, affidavi eal (with appeal fee) in compliance	t, or other evidence, w with 37 CFR 41.31; or	hich places the (3) a Request			
	- Filtra Pro-II - Constru					
The period for reply expires 1 months from the mailing date The period for reply expires on: (1) the mailing date of this A no event, however, will the statutory period for reply expire is	dvisory Action, or (2) the date set forth ater than SIX MONTHS from the mailing	date of the final rejection	n.			
Examiner Note: If box 1 is checked, check either box (a) or (b). ONLY CHECK BOX (b) WHEN THE FIRST REPLY WAS FILED WITHIN TV MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f).						
Extensions of time may be obtained under 37 CFR 1.136(a). The date have been filed is the date for purposes of determining the period act under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the set forth in (a) above, if checket. Any reply received by the Office later may reduce any earned patent term adjustment. See 37 CFR 1.704(b). NOTICE OF APPEAL	on which the petition under 37 CFR 1.1 ension and the corresponding amount hortened statutory period for reply origi than three months after the mailing dat	of the fee. The appropria nally set in the final Offic	ate extension fee e action; or (2) as			
 The Notice of Appeal was filed on A brief in comp filing the Notice of Appeal (37 CFR 41.37(a)), or any exter Notice of Appeal has been filed, any reply must be filed with 	sion thereof (37 CFR 41.37(e)), to	avoid dismissal of the				
AMENDMENTS						
The proposed amendment(s) filed after a final rejection, be (a) They raise new issues that would require further core. Approximately 1.00 They raise new issues that would require further core.	nsideration and/or search (see NO		cause			
 (b) They raise the issue of new matter (see NOTE belown (c) They are not deemed to place the application in better appeal; and/or 		lucing or simplifying th	ne issues for			
(d) They present additional claims without canceling a c	corresponding number of finally reject	cted claims.				
NOTE: (See 37 CFR 1.116 and 41.33(a)).						
4. The amendments are not in compliance with 37 CFR 1.12	1. See attached Notice of Non-Co	mpliant Amendment (F	PTOL-324).			
Applicant's reply has overcome the following rejection(s):						
Newly proposed or amended claim(s) would be all non-allowable claim(s).						
7. for purposes of appeal, the proposed amendment(s) a) will not be entered, or b) will be entered and an explanation of how the new or amended claims would be rejected is provided below or appended. The status of the claim(s) is (or will be) as follows:						
Claim(s) allowed:						
Claim(s) objected to:						
Claim(s) rejected: Claim(s) withdrawn from consideration:						
AFFIDAVIT OR OTHER EVIDENCE						
The affidavit or other evidence filed after a final action, but because applicant failed to provide a showing of good and was not earlier presented. See 37 CFR 1.116(e).						
9. The affidavit or other evidence filed after the date of filing entered because the affidavit or other evidence failed to o showing a good and sufficient reasons why it is necessary.	vercome <u>all</u> rejections under appea	l and/or appellant fails	s to provide a			
10. The affidavit or other evidence is entered. An explanation REQUEST FOR RECONSIDERATION/OTHER						
The request for reconsideration has been considered but See Continuation Sheet.	does NOT place the application in	condition for allowan	ce because:			
12. Note the attached Information <i>Disclosure Statement</i> (s). (13. Other:	PTO/SB/08) Paper No(s)					
Minary Hanney						
/Minsun Harvey/ Supervisory Patent Examiner, Art Unit 2828	/Delma R. Fordé/ Examiner, Art Unit 2828					

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Continuation of 11. does NOT place the application in condition for allowance because: the pressure contact bonded in a manner to remain fixed without adhesive after the pressure has been removed the subject matter not properly described in the application as filed, and provide an explanation of your position. The applicants don't have any support in the specification to explain how pressure contact bonded in a manner to remain fixed without adhesive after the pressure has been removed. The applicants need to provide support on the specification.

One skilled in the art would be quite familiar with the results of optical contact bonding ("Standard optical contacting methods are used, well known in the industry' page 10, line 18). Further, this same paragraph teaches that the elements should be anneated at high temperature. As noted above, annealing improves the shear strength of the bond. If the bond were not fixed, there would be no need to anneal the bond. The examiner disagrees with the applicant arguments since the page 10, lines 13 - 24, saich: it is preferably no pitically contacting a diamond (CVD, natural or type IIs-synthetic) or any other highly thermally conductive heat spreader material to a semiconductor epitaxial layer structure, that the surfaces of both the layer structure and the heat spreader be very clean and very flat, preferably lighter than 0.2 waves at 635 mm. Standard optical contacting methods are used, well known in the industry. Regarding cleaniness, it is preferable that contacting be carried out on a class 100 clean bench and that surfaces be finally cleaned with an organic solvent such as acetone, methanol and iso-propanol. Once the heat spreader and the semiconductor chip are clean, one edge of the semiconductor chip is pressed against the heat spreader and the surfaces are brought into contact with pressure. This usually requires multiple attempts of recleaning and contacting. Once a full surface optical contact has been made, the contacted, assembled structure is anneally assured at temperature between 25 100 C and 350 C. The examiner read very carefully page 10, lines 13 - 24 and don't have any support in the specification to explain how pressure contact bonded in a manner to remain fixed without adhesive after the pressure has been removed. The examiner believe the applicant accept the standard optical contacting methods are used, well known in the industry and is not new on the industry.